



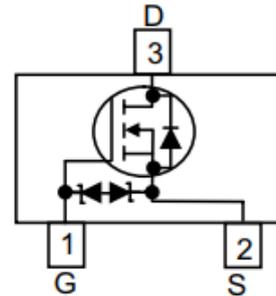
**N-Channel MOSFET with ESD Protection**

➤ **Features**

VDS	VGS	RDSON Typ.	ID	ESD
60V	±20V	1.1R@10V	0.44A	500V
		1.4R@4V5		

➤ **Pin configuration**

Top view

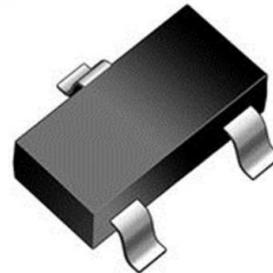


➤ **Description**

This device is an N-Channel enhancement mode MOSFET, with ESD protection, high density cell design, fast switching speed and low threshold voltage.

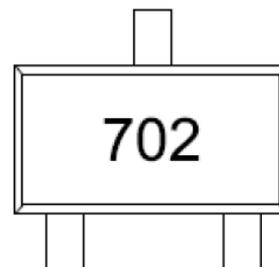
➤ **Applications**

- Small Signal Switch
- Load Switch for Portable Devices
- Battery Operated System



➤ **Ordering Information**

Device	Package	Shipping
SSC8164GS7	SOT323	3000/Reel



Marking



➤ **Absolute Maximum Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	60	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>a</sup>	0.44	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	1.76	A
$P_D$	Power Dissipation <sup>c</sup>	1.25	W
$T_J$	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	100	$^{\circ}\text{C}/\text{W}$

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user's specific board design.
- Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^{\circ}\text{C}$ .
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using steady state junction-to-ambient thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

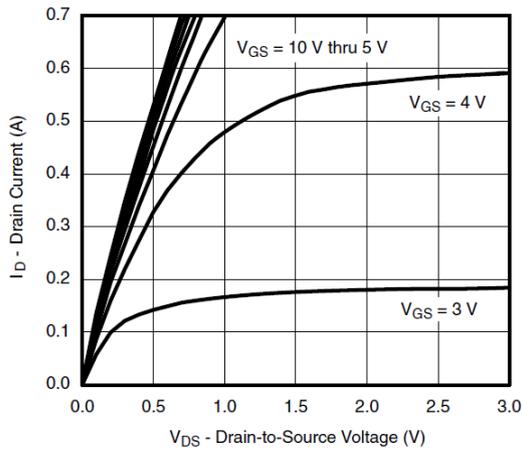


➤ **Electronics Characteristics**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

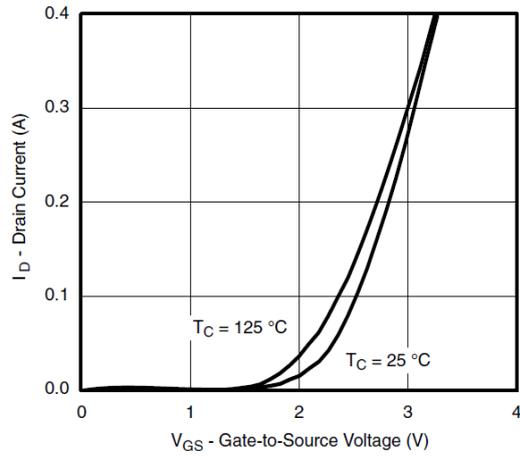
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.7	0.95	1.3	V
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=10V, I_D=0.4A$		1.1	2.5	R
		$V_{GS}=4.5V, I_D=0.3A$		1.4	3.2	
		$V_{GS}=2.5V, I_D=0.1A$		1.8	4	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=48V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 15V, V_{DS}=0V$			$\pm 10$	$\mu A$
$G_{FS}$	Transconductance	$V_{DS}=10V, I_D=0.2A$		0.1		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, I_S=0.2A$		0.7	1.3	V
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, f=1MHz$		35		pF
$C_{oss}$	Output Capacitance			7.2		
$C_{rss}$	Transfer Capacitance			4.7		
$T_{D(ON)}$	Turn-on delay time	$V_{GS}=10V, R_G=1R$ $V_{DS}=30V, I_D=0.44A$		6		ns
$T_r$	Rise Time			12		
$T_{D(OFF)}$	Turn-off delay time			13		
$T_f$	Fall Time			4		
$Q_G$	Total Gate Charge	$V_{GS}=10V, V_{DS}=30V,$ $I_D=0.44A$		1		nC
$Q_{GS}$	Gate Source Charge			0.2		
$Q_{GD}$	Gate Drain Charge			0.15		



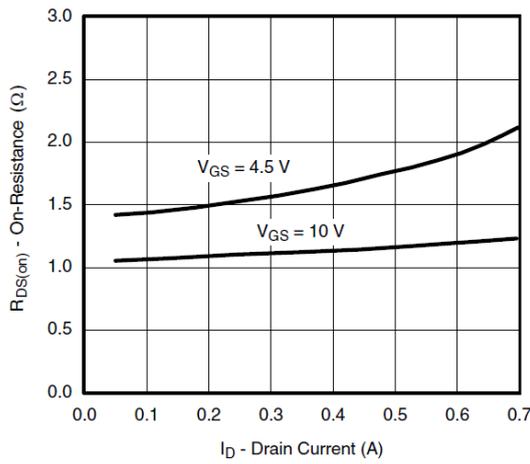
➤ **Typical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)



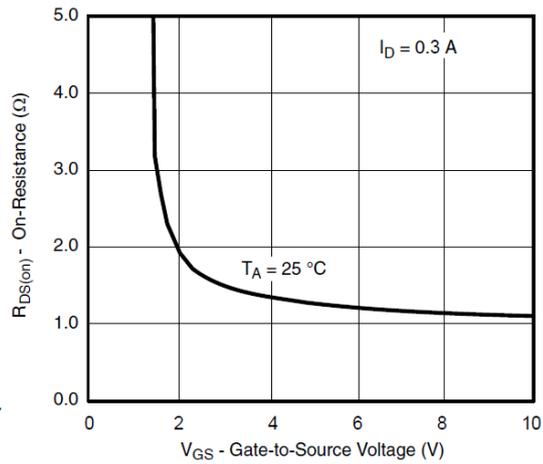
**Output Characteristics**



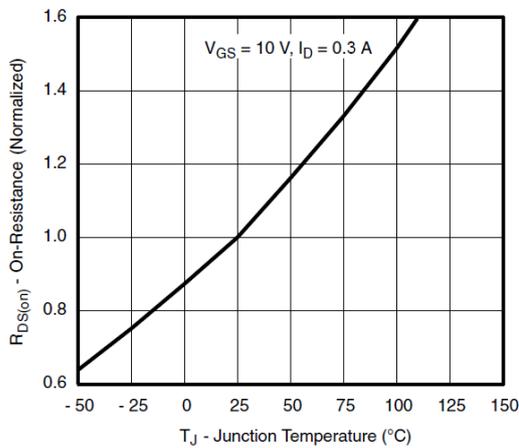
**Transfer Characteristics**



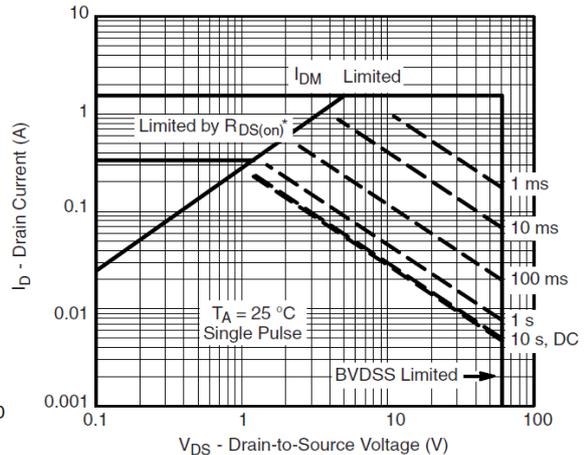
**On-Resistance vs. Drain Current**



**$R_{DS(on)}$  vs.  $V_{GS}$**



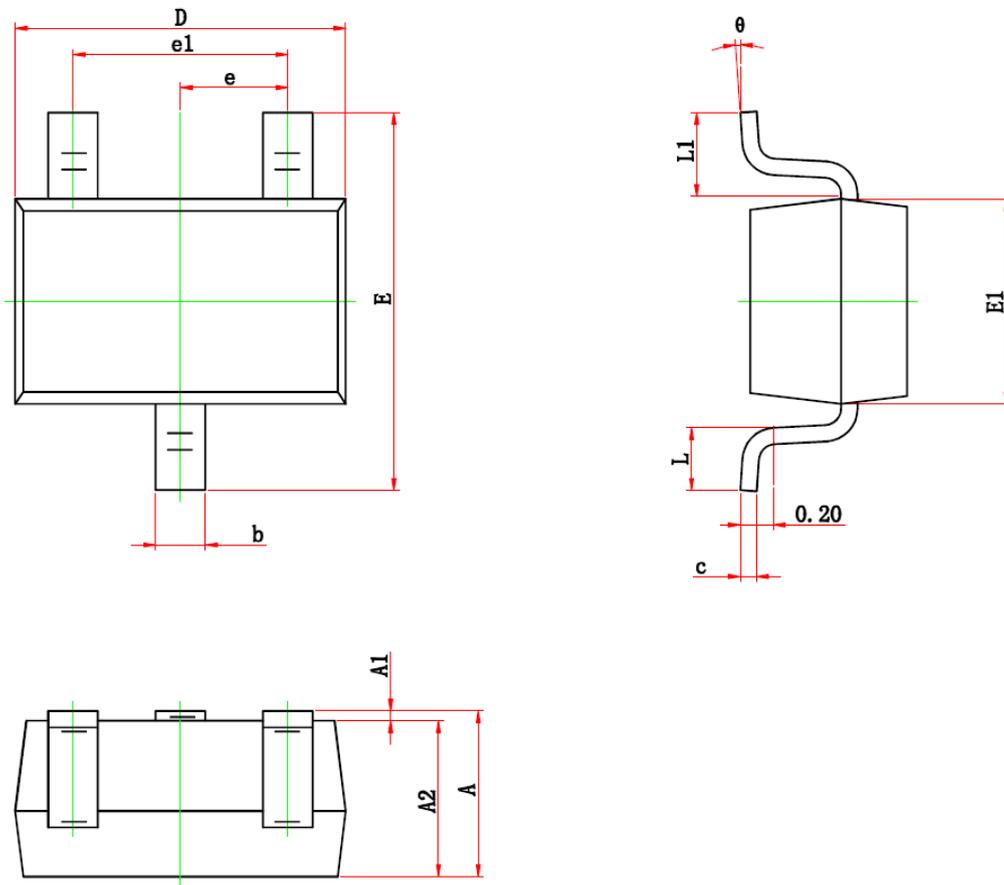
**On-Resistance vs. Junction Temperature**



**Safe Operating Area**  
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



➤ Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	2.150	2.450	0.085	0.096
E1	1.150	1.350	0.045	0.053
e	0.650 TYP.		0.026 TYP.	
e1	1.200	1.400	0.047	0.055
L	0.260	0.460	0.010	0.018
L1	0.525 REF.		0.021 REF.	
θ	0°	8°	0°	8°



---

**DISCLAIMER**

AFSEMI RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. AFSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICIENCE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

THE GRAPHS PROVIDED IN THIS DOCUMENT ARE STATISTICAL SUMMARIES BASED ON A LIMITED NUMBER OF SAMPLES AND ARE PROVIDED FOR INFORMATIONAL PURPOSE ONLY. THE PERFORMANCE CHARACTERISTICS LISTED IN THEM ARE NOT TESTED OR GUARANTEED. IN SOME GRAPHS, THE DATA PRESENTED MAY BE OUTSIDE THE SPECIFIED OPERATING RANGE (E.G. OUTSIDE SPECIFIED POWER SUPPLY RANGE) AND THEREFORE OUTSIDE THE WARRANTED RANGE.